

Silicon Carbide (SiC) MOSFET - EliteSiC, 32 mohm, 650 V, M3S, TO247-4L, THIN LEADS NTH4LN032N065M3S

Features

- Typical $R_{DS(ON)} = 32 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge ($Q_{G(tot)} = 55 \text{ nC}$)
- High Speed Switching with Low Capacitance ($C_{OSS} = 114 \text{ pF}$)
- 100% Avalanche Tested
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

Applications

- SMPS, Solar Inverters, UPS, Energy Storage, EV Charging Infrastructure

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

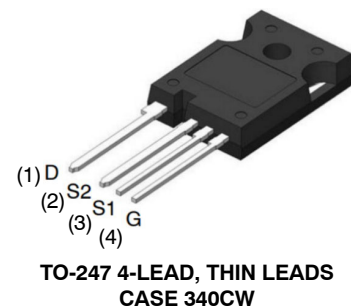
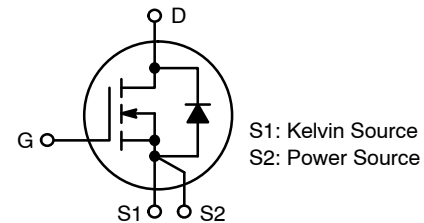
Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	650	V
Gate-to-Source Static Voltage	V_{GS}	-10/ +22.6	V
Gate-to-Source Transient Voltage	$t_p < 0.5 \mu\text{s}$, Duty Cycle $\leq 1\%$	V_{GS}	-11/ +25
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	50
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	187
Continuous Drain Current (Note 1)	$T_C = 100^\circ\text{C}$	I_D	30
Power Dissipation	$T_C = 100^\circ\text{C}$	P_D	94
Pulsed Drain Current (Note 2)	$T_C = 25^\circ\text{C}$, $t_p = 100 \mu\text{s}$	I_{DM}	163
Continuous Source-Drain Current (Body Diode)	$T_C = 25^\circ\text{C}$, $V_{GS} = -3 \text{ V}$	I_S	29
	$T_C = 100^\circ\text{C}$, $V_{GS} = -3 \text{ V}$		16
Pulsed Source-Drain Current (Body Diode) (Note 2)	$T_C = 25^\circ\text{C}$, $V_{GS} = -3 \text{ V}$, $t_p = 100 \mu\text{s}$	I_{SM}	137
Single Pulse Avalanche Energy ($I_{LPK} = 16.7 \text{ A}$, $L = 1 \text{ mH}$) (Note 3)	E_{AS}	139	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	$^\circ\text{C}$
Lead Temperature for Soldering Purposes (1/8" from case for 10 secs)	T_L	270	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. 30 A is limited by package. Power chip max drain current is 35 A if limited by max junction temperature.
2. Single pulse, limited by max junction temperature.
3. E_{AS} of 139 mJ is based on starting $T_J = 25^\circ\text{C}$, $L = 1 \text{ mH}$, $I_{AS} = 16.7 \text{ A}$, $V_{DD} = 100 \text{ V}$, $V_{GS} = 18 \text{ V}$.

$V_{(BR)DSS}$	$R_{DS(ON)}$ TYP	I_D MAX
650 V	32 m Ω @ 18 V	50 A

N-CHANNEL MOSFET



MARKING DIAGRAM



4LN032065M3S = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTH4LN032N065M3S	TO247-4L, Thin Leads	30 Units / Tube

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note 4)	$R_{\theta JC}$	0.80	°C/W
Thermal Resistance, Junction-to-Ambient (Note 4)	$R_{\theta JA}$	40	

4. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value	Unit
Operation Values of Gate-to-Source Voltage	V_{GSop}	-5...0 +18	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

* Operation at 0 V turn-off requires consideration of switching behavior and system-level design trade-offs. Design guidance and application considerations are provided in Application Note [AND90255/D](#).

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
-----------	--------	-----------------	-----	-----	-----	------

OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25\text{ °C}$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650\text{ V}, T_J = 25\text{ °C}$			10	μA
		$V_{DS} = 650\text{ V}, T_J = 175\text{ °C}$ (Note 6)			500	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS} = -10/+22.6\text{ V}, V_{DS} = 0\text{ V}$			± 1.0	μA

ON CHARACTERISTICS

Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 18\text{ V}, I_D = 15\text{ A}, T_J = 25\text{ °C}$		32	44	$\text{m}\Omega$
		$V_{GS} = 18\text{ V}, I_D = 15\text{ A}, T_J = 175\text{ °C}$ (Note 6)		49		
		$V_{GS} = 15\text{ V}, I_D = 15\text{ A}, T_J = 25\text{ °C}$		41		
		$V_{GS} = 15\text{ V}, I_D = 15\text{ A}, T_J = 175\text{ °C}$ (Note 6)		52		
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 7.5\text{ mA}, T_J = 25\text{ °C}$	2.0	2.7	4.0	V
Forward Transconductance	g_{FS}	$V_{DS} = 10\text{ V}, I_D = 15\text{ A}$ (Note 6)		9.9		S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ (Note 6)		1410		pF
Output Capacitance	C_{OSS}			114		
Reverse Transfer Capacitance	C_{RSS}			9.2		
Total Gate Charge	$Q_{G(TOT)}$	$V_{DD} = 400\text{ V}, I_D = 15\text{ A}, V_{GS} = -3/18\text{ V}$ (Note 6)		55		nC
Gate-to-Source Charge	Q_{GS}			15		
Gate-to-Drain Charge	Q_{GD}			14		
Gate Resistance	R_G	$f = 1\text{ MHz}$		5.0		Ω

SWITCHING CHARACTERISTICS

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}, V_{DD} = 400\text{ V}, I_D = 15\text{ A}, R_G = 4.7\text{ }\Omega, T_J = 25\text{ °C}$ (Notes 5, 6)		8.8		ns
Turn-Off Delay Time	$t_{d(OFF)}$			31		
Rise Time	t_r			12		
Fall Time	t_f			9		
Turn-On Switching Loss	E_{ON}			33		μJ
Turn-Off Switching Loss	E_{OFF}			16		
Total Switching Loss	E_{TOT}			49		

NTH4LN032N065M3S

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}$, $V_{DD} = 400\text{ V}$, $I_D = 15\text{ A}$, $R_G = 4.7\text{ }\Omega$, $T_J = 175\text{ }^{\circ}\text{C}$ (Notes 5, 6)		7.8		ns
Turn-Off Delay Time	$t_{d(OFF)}$			37		
Rise Time	t_r			12		
Fall Time	t_f			11		
Turn-On Switching Loss	E_{ON}			31		μJ
Turn-Off Switching Loss	E_{OFF}			25		
Total Switching Loss	E_{TOT}			56		

SOURCE-TO-DRAIN DIODE CHARACTERISTICS

Continuous Source-Drain Diode Forward Current	I_{SD}	$V_{GS} = -3\text{ V}$, $T_C = 25\text{ }^{\circ}\text{C}$ (Note 6)			29	A
Pulsed Source-Drain Diode Forward Current (Note 2)	I_{SDM}				137	
Forward Diode Voltage	V_{SD}	$I_{SD} = 15\text{ A}$, $V_{GS} = -3\text{ V}$, $T_J = 25\text{ }^{\circ}\text{C}$		4.5		V
		$I_{SD} = 15\text{ A}$, $V_{GS} = -3\text{ V}$, $T_J = 175\text{ }^{\circ}\text{C}$ (Note 6)		4.2		
Reverse Recovery Time	t_{RR}	$V_{GS} = -3\text{ V}$, $I_S = 15\text{ A}$, $di/dt = 1000\text{ A}/\mu\text{s}$, $V_{DS} = 400\text{ V}$ (Note 6)		15.5		ns
Charge Time	t_a			8.9		
Discharge Time	t_b			6.6		
Reverse Recovery Charge	Q_{RR}			72		nC
Reverse Recovery Energy	E_{REC}			4.6		μJ
Peak Reverse Recovery Current	I_{RRM}			9.3		A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. E_{ON}/E_{OFF} result is with body diode.

6. Defined by design, not subject to production test.

TYPICAL CHARACTERISTICS

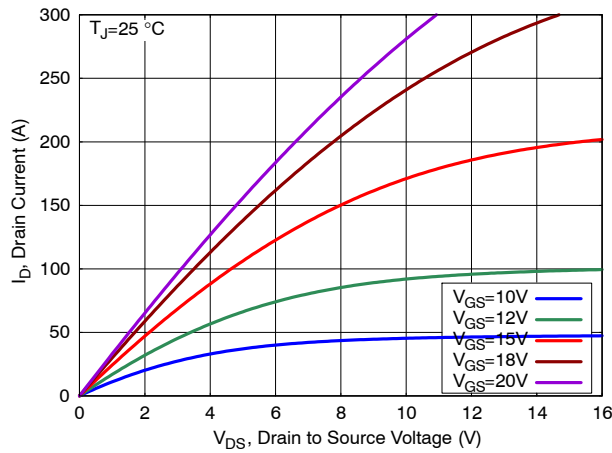


Figure 1. On-Region Characteristics

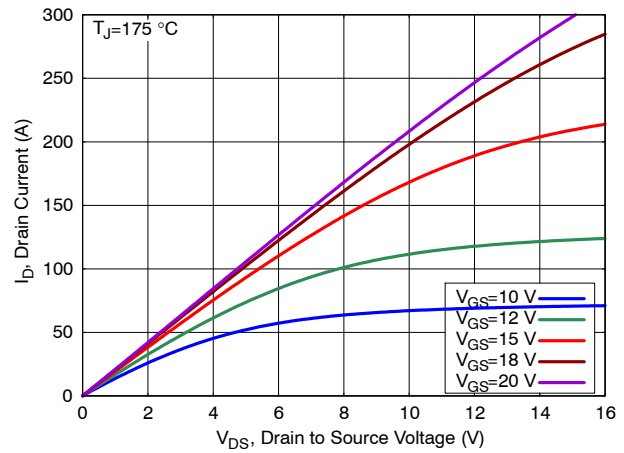


Figure 2. Output Characteristics

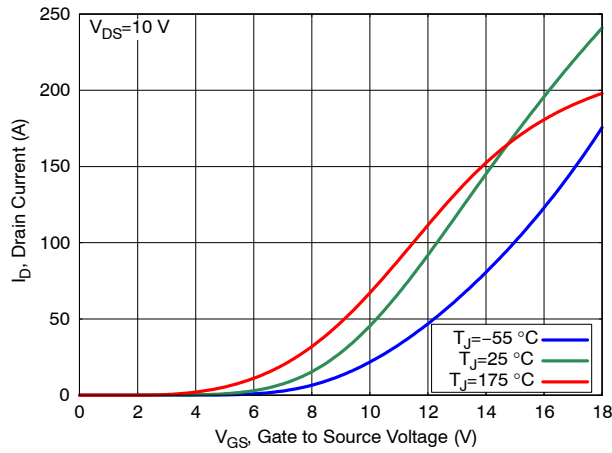


Figure 3. Transfer Characteristics

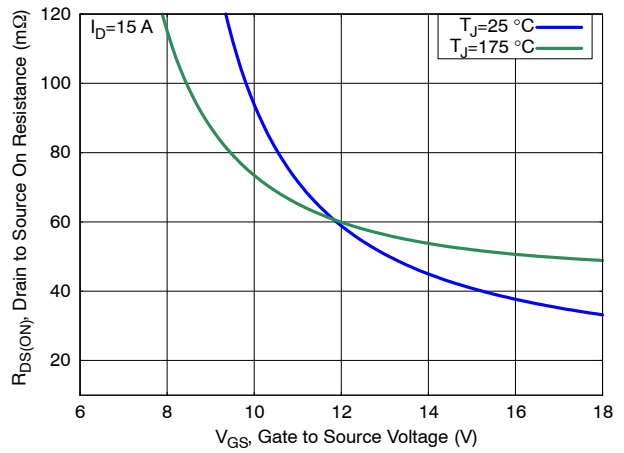


Figure 4. On-Resistance vs. Gate Voltage

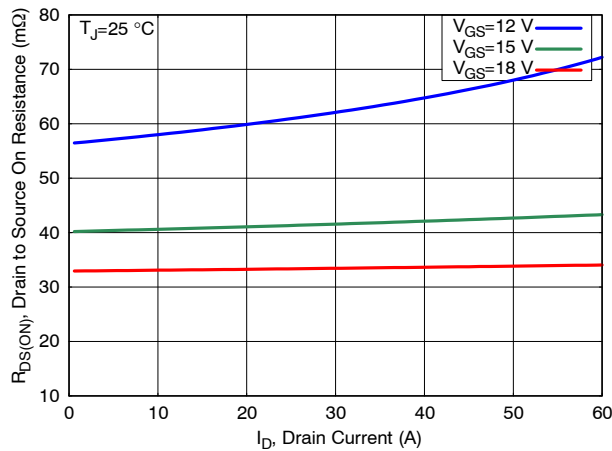


Figure 5. On-Resistance vs. Drain Current

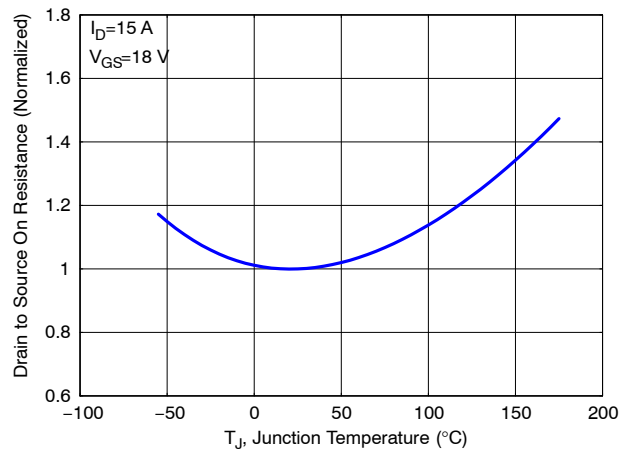


Figure 6. On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS

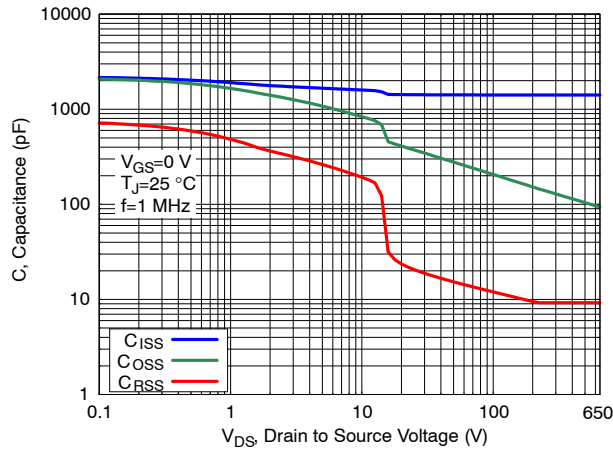


Figure 7. Capacitance Characteristics

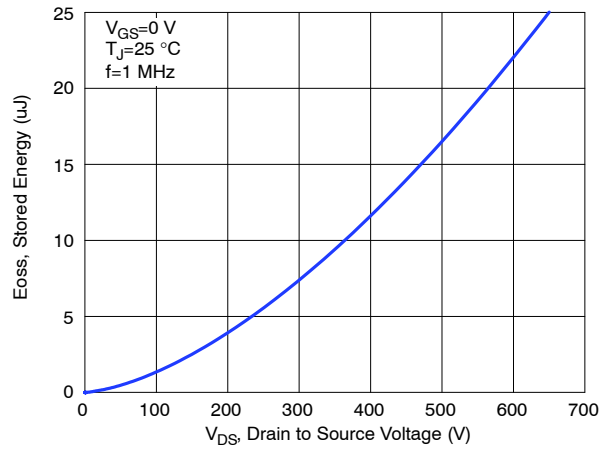


Figure 8. Stored Energy vs. Drain-to-Source Voltage

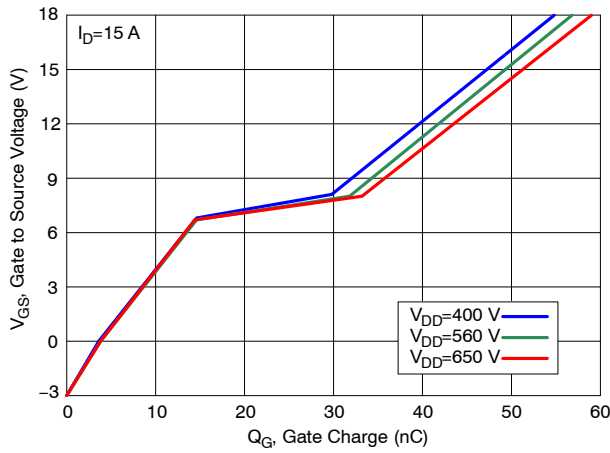


Figure 9. Gate Charge Characteristics

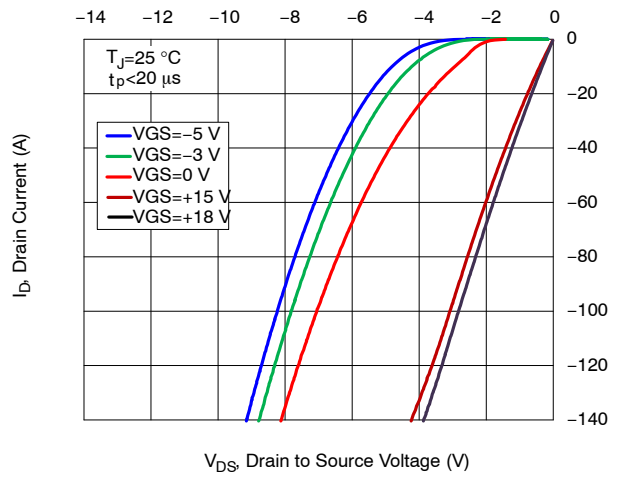


Figure 10. Reverse Conduction Characteristics

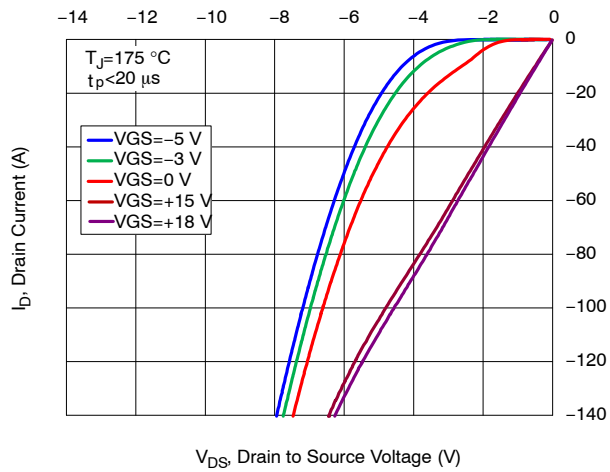


Figure 11. Reverse Conduction Characteristics

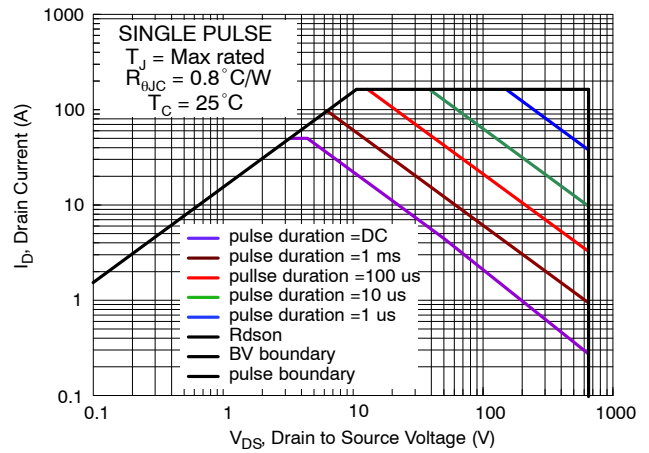


Figure 12. Safe Operating Area

TYPICAL CHARACTERISTICS

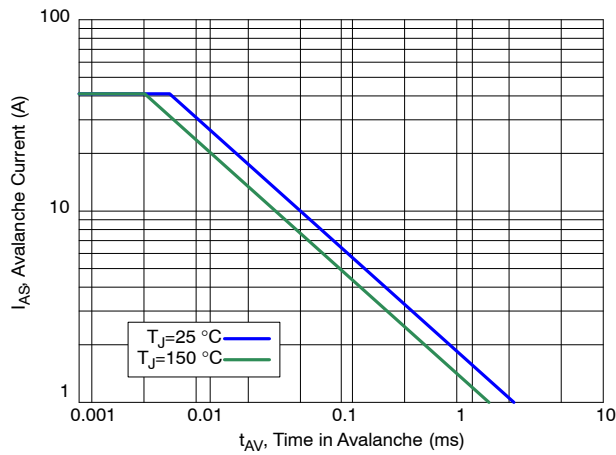


Figure 13. Avalanche Current vs. Pulse Time (UIS)

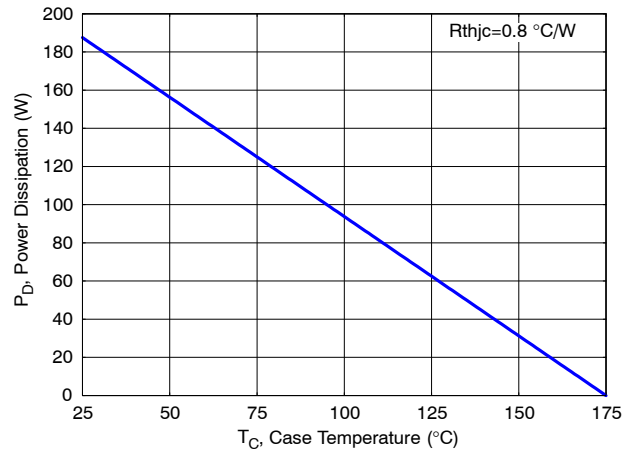


Figure 14. Maximum Power Dissipation vs. Case Temperature

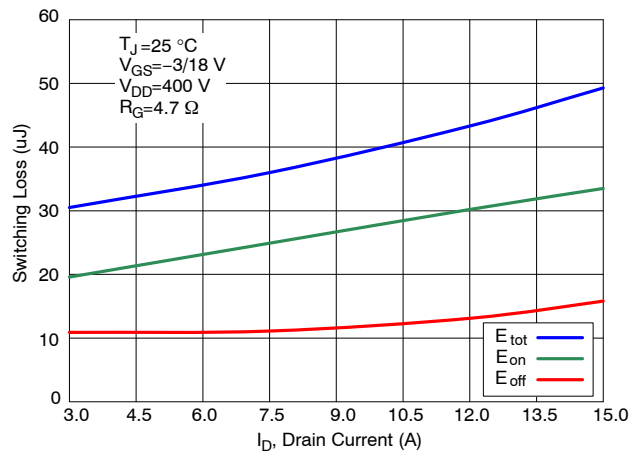


Figure 15. Inductive Switching Loss vs. Drain Current

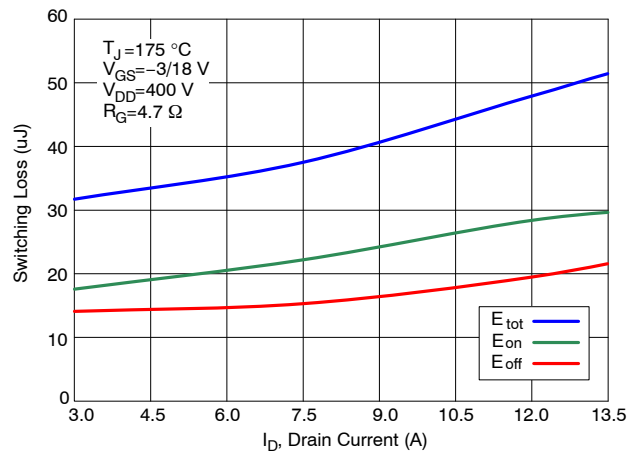


Figure 16. Inductive Switching Loss vs. Drain Current

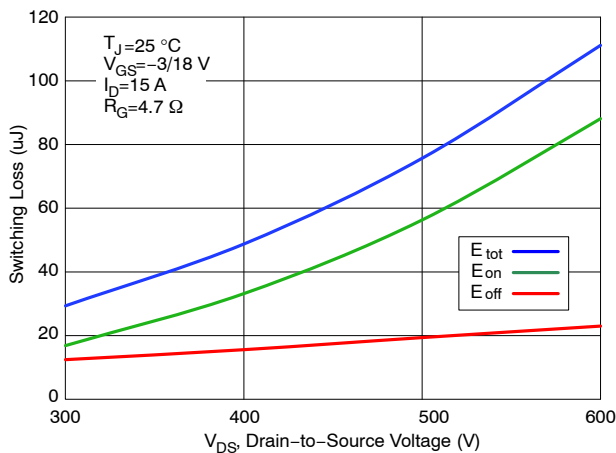


Figure 17. Inductive Switching Loss vs. Drain Voltage

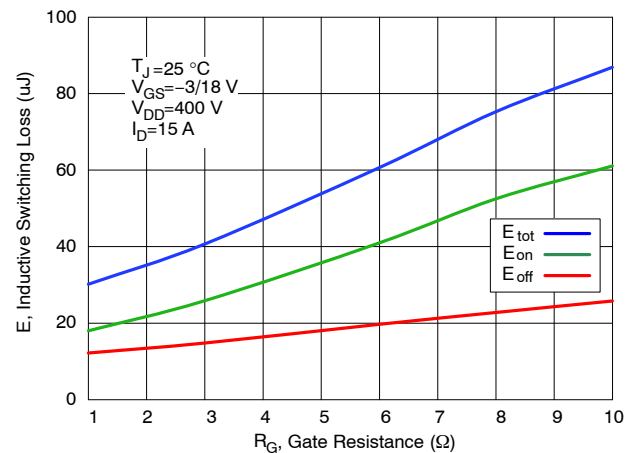


Figure 18. Inductive Switching Loss vs. Gate Resistance

NTH4LN032N065M3S

TYPICAL CHARACTERISTICS

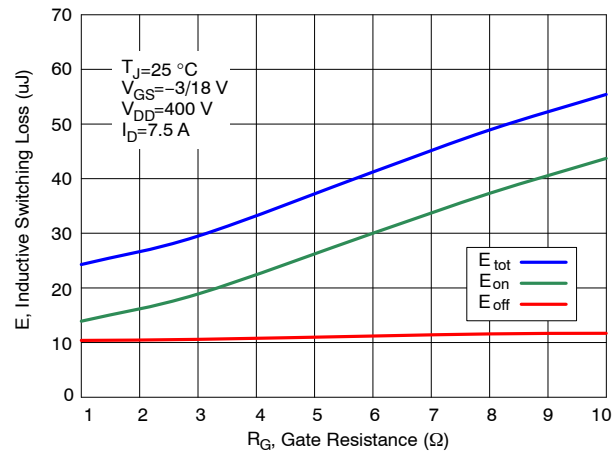


Figure 19. Inductive Switching Loss vs. Gate Resistance

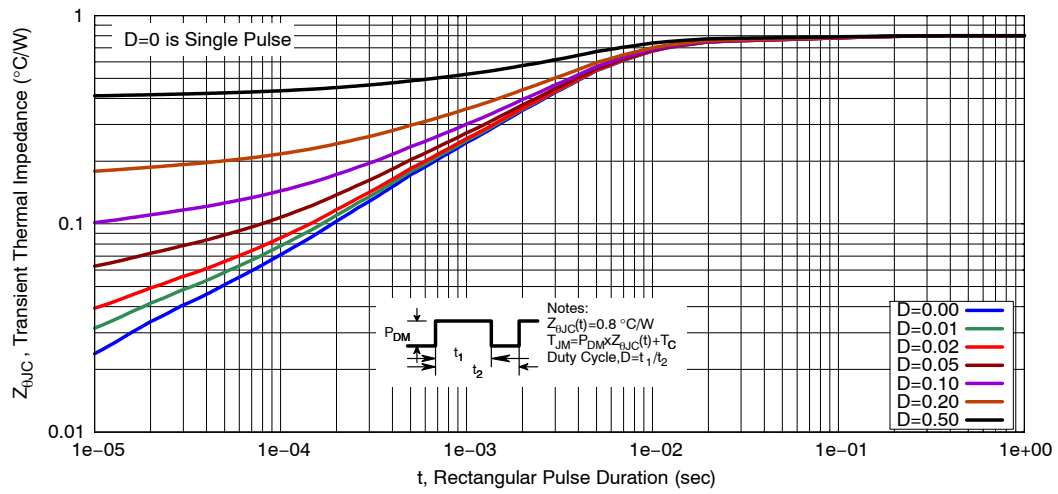


Figure 20. Thermal Response Characteristics

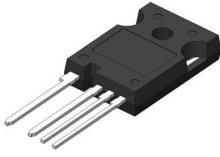
NTH4LN032N065M3S

REVISION HISTORY

Revision	Description of Changes	Date
0	Initial document release	7/31/2026

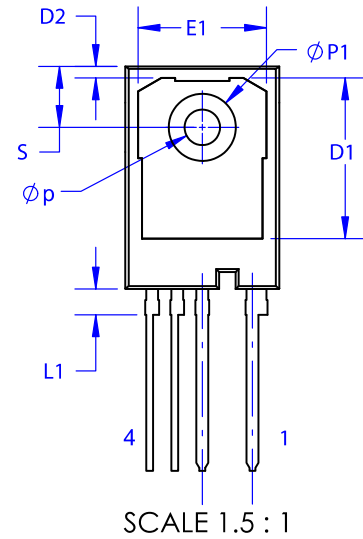
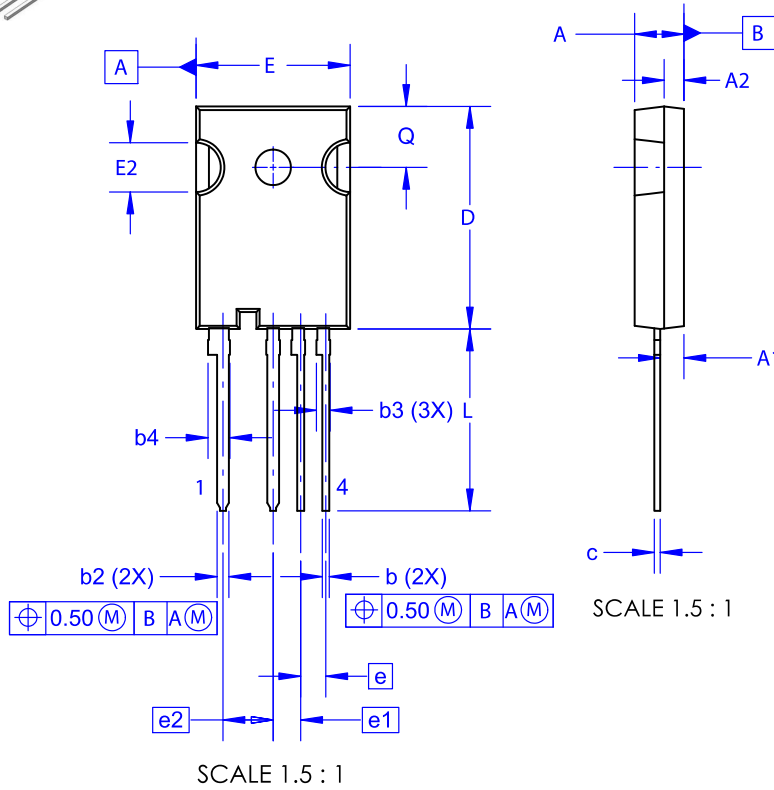
NTH4LN032N065M3S

PACKAGE DIMENSIONS



TO-247 4-LEAD, THIN LEADS
CASE 340CW
ISSUE A

DATE 16 SEP 2019



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	0.57	0.70	0.83
b2	1.07	1.20	1.33
b3	1.20	1.40	1.60
b4	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.30	16.50
D2	0.97	1.17	1.37
e		2.54	
e1		2.79	
e2		5.08	
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E2	4.80	5.00	5.20
L	18.12	18.42	18.72
L1	2.42	2.62	2.82
phi p	3.40	3.60	3.80
phi P1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Markings.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales